

ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	$V_{\rm F}$	$I_F = 10 \text{mA}$	1.0	1.15	1.3	V
Reverse Voltage	V_R	$I_R = 10\mu A$	6.0			V
Reverse Leakage	I_R	$V_R = 4V$			10	μΑ
Terminal Capacitance	C_{t}	V = 0V, $f = 1KHz$		30	250	pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector—Emitter breakdown Voltage	BV_{CEO}	$I_{C} = 0.5 \text{mA}, I_{F} = 0 \text{mA}$	55			V
Emitter—Collector breakdown Voltage	$\mathrm{BV}_{\mathrm{ECO}}$	$I_E = 100 \mu A, I_F = 0 mA$	6			V
Collector-Emitter Dark Current	I_{CEO}	$V_{CE} = 20V$, $I_F = 0mA$			100	nA



ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

COUPLED

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	$I_F = 5\text{mA}, V_{CE} = 5V$	50		600	%
		Optional CTR Grades $GR \\ BL \\ GB \\ GB \ (I_F = 1 mA, V_{CE} = 0.4 V)$	100 200 100 30		300 600 600	
Collector—Emitter Saturation Voltage	V _{CE(sat)}	$I_F = 8mA, I_C = 2.4mA$ GB ($I_F = 1mA, I_C = 0.2mA$)			0.4 0.4	V
Output Rise Time	$t_{\rm r}$	$V_{CE} = 2V$, Ic = 2mA,		4		μs
Output Fall Time	t_{f}	$R_{L} = 100\Omega$		3		
Turn-on Time	t _{on}			3		
Turn-off Time	$t_{ m off}$			3		
Turn-on Time	t_{ON}	$V_{CC} = 5V$, $I_F = 16mA$,		2		μs
Turn-off Time	$t_{ m OFF}$	$R_L = 1.9k\Omega$		25		

ISOLATION

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Input to Output Isolation Voltage	$V_{\rm ISO}$	AC 1 minute, RH = 40 to 60% Note 1	5300			V_{RMS}
Input to Output Isolation Resistance	$R_{\rm ISO}$	V _{IO} = 500V Note 1	5x10 ¹⁰			Ω

Note 1: Measure with input leads shorted together and output leads shorted together.



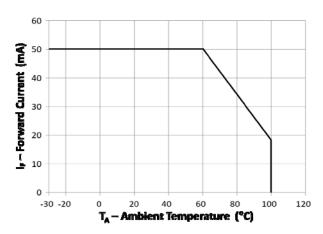


Fig 1 Forward Current vs T_A

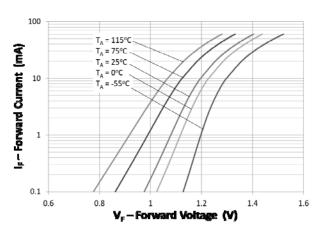


Fig 3 Forward Current vs Forward Voltage

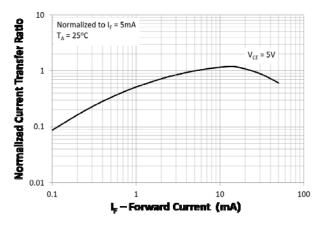


Fig 5 Normalized Current Transfer Ratio vs Forward Current

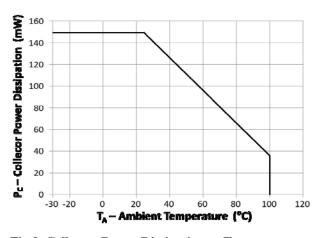


Fig 2 Collector Power Dissipation vs T_A

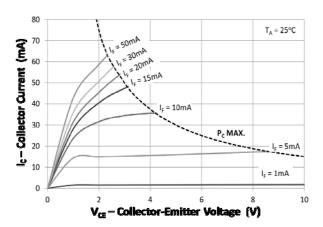


Fig 4 Collector Current vs Collector-Emitter Voltage

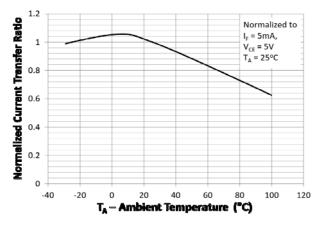


Fig 6 Normalized Current Transfer Ratio vs Ambient Temperature



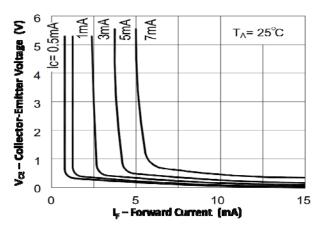


Fig 7 Collector-Emitter Voltage vs Forward Current

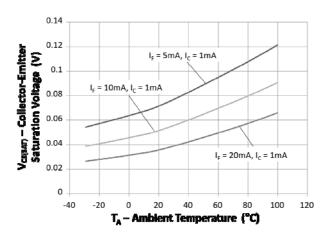


Fig 8 Collector-Emitter Voltage vs Ambient Temperature

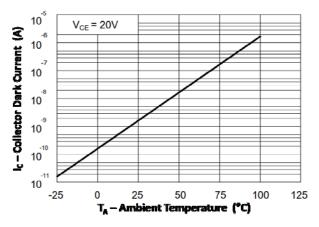


Fig 9 Collector Dark Current vs Ambient Temperture



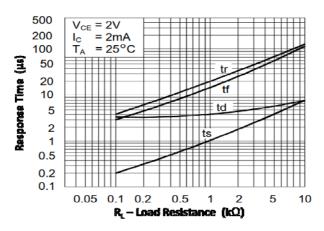
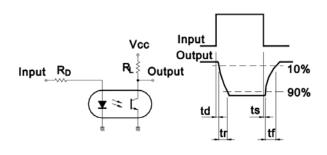


Fig 7 Response Time vs Load Resistance



Response Time Test Circuit

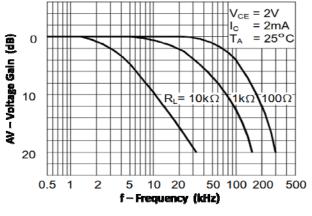
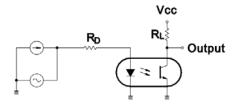


Fig 9 Frequency Response



Frequency Response Test Circuit



ORDER INFORMATION

_	TLP521, TLP521-1 (UL Approval)					
After PN	PN	Description	Packing quantity			
None	TLP521, TLP521-1 TLP521GR, TLP521-1GR TLP521BL, TLP521-1BL, TLP521GB, TLP521-1GB	Standard DIP4	100 pcs per tube			
G	TLP521G, TLP521-1G, TLP521GRG, TLP521-1GRG, TLP521BLG, TLP521-1BLG TLP521GBG, TLP521-1GBG	10mm Lead Spacing	100 pcs per tube			
SM	TLP521SM, TLP521-1SM, TLP521GRSM, TLP521-1GRSM, TLP521BLSM, TLP521-1BLSM, TLP521GBSM, TLP521-1GBSM	Surface Mount	100 pcs per tube			
SMT&R	TLP521SMT&R, TLP521-1SMT&R TLP521GRSMT&R, TLP521-1GRSMT&R, TLP521BLSMT&R, TLP521-1BLSMT&R, TLP521GBSMT&R, TLP521-1GBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel			

Note: Optional Order Part No. TLP521-1 for TLP521.



ORDER INFORMATION

	TLP521-2 (UL Approval)				
After PN	PN	Description	Packing quantity		
None	TLP521-2, TLP521-2GR, TLP521-2BL, TLP521-2GB	Standard DIP8	50 pcs per tube		
G	TLP521-2G, TLP521-2GRG, TLP521-2BLG, TLP521-2GBG	10mm Lead Spacing	50 pcs per tube		
SM	TLP521-2SM, TLP521-2GRSM, TLP521-2BLSM, TLP521-2GBSM	Surface Mount	50 pcs per tube		
SMT&R	TLP521-2SMT&R, TLP521-2GRSMT&R, TLP521-2BLSMT&R, TLP521-2GBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel		

	TLP521-4 (UL Approval)				
After PN	PN	Description	Packing quantity		
None	TLP521-4, TLP521-4GR, TLP521-4BL, TLP521-4GB	Standard DIP16	25 pcs per tube		
G	TLP521-4G, TLP521-4GRG, TLP521-4BLG, TLP521-4GBG	10mm Lead Spacing	25 pcs per tube		
SM	TLP521-4SM, TLP521-4GRSM, TLP521-4BLSM, TLP521-4GBSM	Surface Mount	25 pcs per tube		



ORDER INFORMATION

	TLP521X, TLP521-1X (UL and VDE Approvals)				
After PN	PN	Description	Packing quantity		
None	TLP521X, TLP521-1X TLP521XGR, TLP521-1XGR TLP521XBL, TLP521-1XBL, TLP521XGB, TLP521-1XGB	Standard DIP4	100 pcs per tube		
G	TLP521XG, TLP521-1XG, TLP521XGRG, TLP521-1XGRG, TLP521XBLG, TLP521-1XBLG TLP521XGBG, TLP521-1XGBG	10mm Lead Spacing	100 pcs per tube		
SM	TLP521XSM, TLP521-1XSM, TLP521XGRSM, TLP521-1XGRSM, TLP521XBLSM, TLP521-1XBLSM, TLP521XGBSM, TLP521-1XGBSM	Surface Mount	100 pcs per tube		
SMT&R	TLP521XSMT&R, TLP521-1XSMT&R TLP521XGRSMT&R, TLP521-1XGRSMT&R, TLP521XBLSMT&R, TLP521-1XBLSMT&R, TLP521-1XGBSMT&R, TLP521-1XGBSMT&R,	Surface Mount Tape & Reel	1000 pcs per reel		

Note: Optional Order Part No. TLP521-1 for TLP521.



ORDER INFORMATION

	TLP521-2X (UL and VDE Approvals)				
After PN	PN	Description	Packing quantity		
None	TLP521-2X, TLP521-2XGR, TLP521-2XBL, TLP521-2XGB	Standard DIP8	50 pcs per tube		
G	TLP521-2XG, TLP521-2XGRG TLP521-2XBLG, TLP521-2XGBG	10mm Lead Spacing	50 pcs per tube		
SM	TLP521-2XSM, TLP521-2XGRSM, TLP521-2XBLSM, TLP521-2XGBSM	Surface Mount	50 pcs per tube		
SMT&R	TLP521-2XSMT&R, TLP521-2XGRSMT&R, TLP521-2XBLSMT&R, TLP521-2XGBSMT&R	Surface Mount Tape & Reel	1000 pcs per reel		

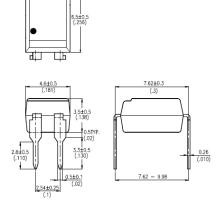
	TLP521-4X (UL and VDE Approvals)					
After PN	PN	Description	Packing quantity			
None	TLP521-4X, TLP521-4XGR, TLP521-4XBL, TLP521-4XGB	Standard DIP16	25 pcs per tube			
G	TLP521-4XG, TLP521-4XGRG, TLP521-4XBLG, TLP521-4XGBG	10mm Lead Spacing	25 pcs per tube			
SM	TLP521-4XSM, TLP521-4XGRSM, TLP521-4XBLSM, TLP521-4XGBSM	Surface Mount	25 pcs per tube			



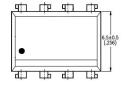
PACKAGE DIMENSIONS in mm (inch)

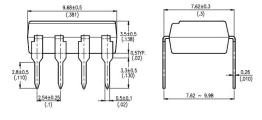
DIP



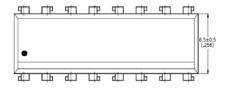


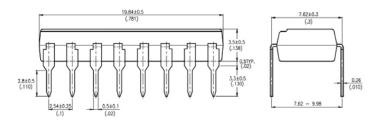
TLP521-2





TLP521-4



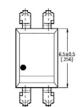


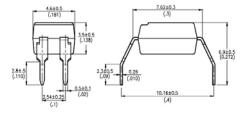


PACKAGE DIMENSIONS in mm (inch)

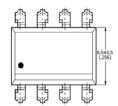
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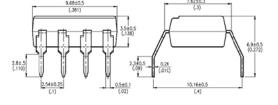
TLP521G



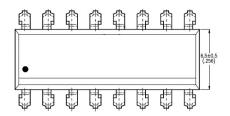


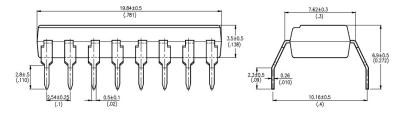
TLP521-2G





TLP521-4G



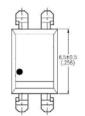


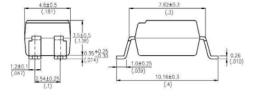


PACKAGE DIMENSIONS in mm (inch)

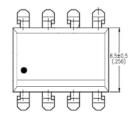
SMD

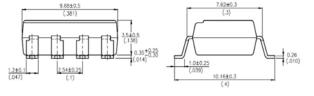
TLP521SM



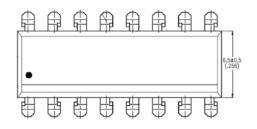


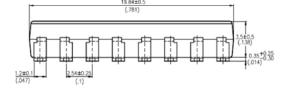
TLP521-2SM

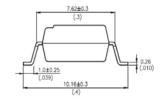




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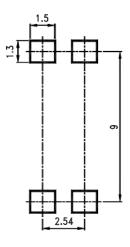




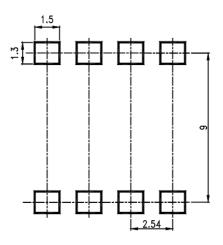


RECOMMENDED PAD LAYOUT FOR SMD (mm)

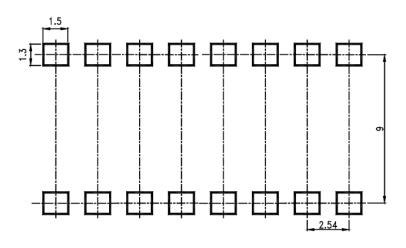


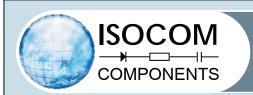


TLP521-2SM

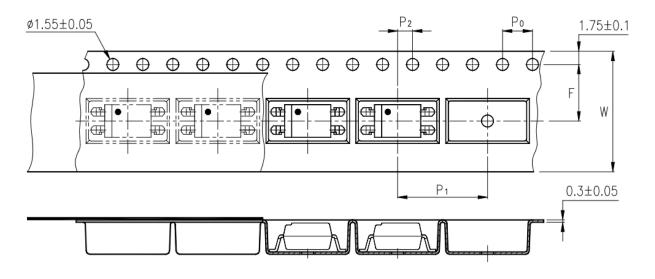


TLP521-4SM

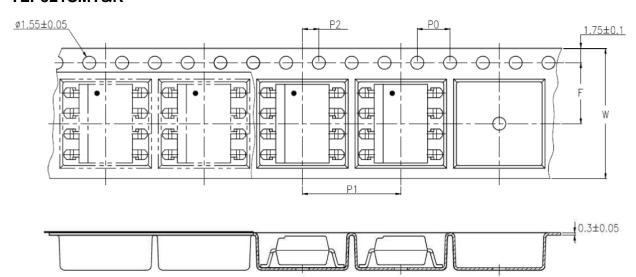




TAPE AND REEL PACKAGING



TLP521SMT&R

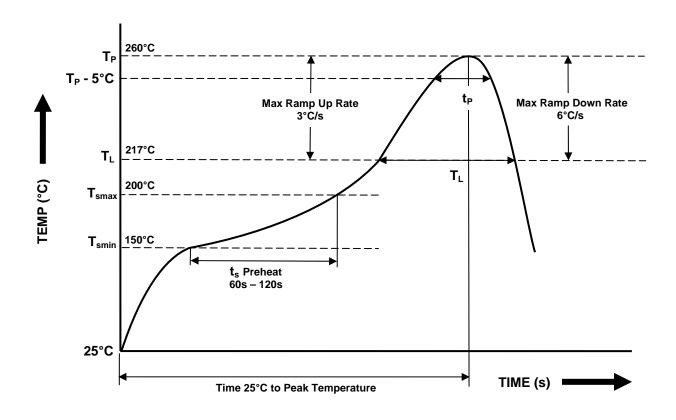


TLP521-2SMT&R

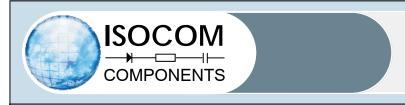
Description	Symbol	Dimensions in mm (inches)
Tape wide	W	$16 \pm 0.3 (.63)$
Pitch of sprocket holes	P ₀	4 ± 0.1 (.15)
Distance of commentment	F	$7.5 \pm 0.1 (.295)$
Distance of compartment	P ₂	$2 \pm 0.1 (.079)$
Distance of compartment to compartment	P ₁	12 ± 0.1 (.472)



IR REFLOW SOLDERING TEMPERATURE PROFILE FOR SMD (One Time Reflow Soldering is Recommended)



Profile Details	Conditions
Preheat - Min Temperature (T _{SMIN}) - Max Temperature (T _{SMAX}) - Time T _{SMIN} to T _{SMAX} (t _s)	150°C 200°C 60s - 120s
$\begin{tabular}{ll} \textbf{Soldering Zone} \\ - & \begin{tabular}{ll} - & \begin{tabular}{ll} \textbf{Peak Temperature } & \begin{tabular}{ll} - & \begin{tabular}{ll} \textbf{Peak Temperature } & \begin{tabular}{l$	260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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